



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CYNB*0158BG6	A	Z6HA	2017-01-04
Amount	UoM	Unit type	ST ECOPACK Grade	
8.07	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2x2x0.6	8	No lead	
Comment	Package: NB UFSON 2x2x0.6 8 PITCH 0.5; MDF valid for LM358QT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CYNB*01588G6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.413	mg	supplier	die	Silicon (Si)	7440-21-3		0.400	mg	968523	49566
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	14528	743
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	7264	372
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	9685	496
Leadframe	Copper & its alloys	2.728	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.508	mg	919355	310781
				supplier	alloy	Iron (Fe)	7439-89-6		0.004	mg	1466	496
				supplier	alloy	Nickel (Ni)	7440-02-0		0.132	mg	48387	16357
				supplier	alloy	Zinc (Zn)	7440-66-6		0.019	mg	6965	2354
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.006	mg	2199	743
				supplier	alloy	Silicon (Si)	7440-21-3		0.019	mg	6965	2354
				supplier	alloy	Manganese (Mn)	7439-96-5		0.002	mg	733	248
				supplier	metallization	Silver (Ag)	7440-22-4		0.038	mg	13930	4709
Die attach	Other Organic Materials	0.140	mg	supplier	glue	Aluminium oxide	1344-28-1		0.042	mg	300000	5204
				supplier	glue	Diethylene glycol monoethyl ether acetate	112-15-2		0.056	mg	400000	6939
				supplier	glue	Epoxy resin	25068-38-6		0.010	mg	71429	1239
				supplier	glue	Epoxy resin	Proprietary		0.028	mg	200000	3470
Bonding wires	Precious metals	0.083	mg	supplier	wire	Gold (Au)	7440-57-5		0.083	mg	1000000	10285
				supplier	glue	Aromatic amine	Proprietary		0.004	mg	28571	496
Encapsulation	Other Organic Materials	4.511	mg	supplier	mold compound	Silica Fused	60676-86-0		4.070	mg	902239	504337
				supplier	mold compound	Epoxy Resin	Proprietary		0.210	mg	46553	26022
				supplier	mold compound	Phenol Resin	Proprietary		0.210	mg	46553	26022
connections coating	Solder	0.195	mg	supplier	mold compound	Carbon Black	1333-86-4		0.021	mg	4655	2602
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.195	mg	1000000	24164